

# HSB88WK

Silicon Schottky Barrier Diode for High Speed Switching

# HITACHI

ADE-208-1042 (Z)  
Rev. 0  
Jan. 2001

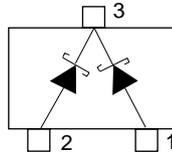
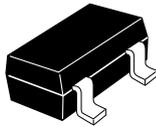
## Features

- Proof against high voltage.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

## Ordering Information

Type No.	Laser Mark	Package Code
HSB88WK	C4	CMPAK

## Outline



(Top View)

1. Anode
2. Anode
3. Cathode

## Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	$V_R$	10	V
Average rectified current	$I_O^{*1}$	15	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: Per one device.

## Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_{F1}$	350	—	420	mV	$I_F = 1 \text{ mA}$
	$V_{F2}$	500	—	580		$I_F = 10 \text{ mA}$
Reverse current	$I_{R1}$	—	—	0.2	$\mu\text{A}$	$V_R = 2\text{V}$
	$I_{R2}$	—	—	10		$V_R = 10\text{V}$
Capacitance	C	—	—	0.80	pF	$V_R = 0\text{V}$ , $f = 1 \text{ MHz}$
Capacitance deviation	$\Delta C$	—	—	0.10	pF	$V_R = 0\text{V}$ , $f = 1 \text{ MHz}$
Forward voltage deviation	$\Delta V_F$	—	—	10	mV	$I_F = 10 \text{ mA}$
ESD-Capability <sup>*1</sup>	—	30	—	—	V	C = 200 pF, R = 0 $\Omega$ , Both forward and reverse direction 1 pulse.

Note: Failure criterion ;  $I_R > 0.4\mu\text{A}$  at  $V_R = 2 \text{ V}$

Main Characteristic

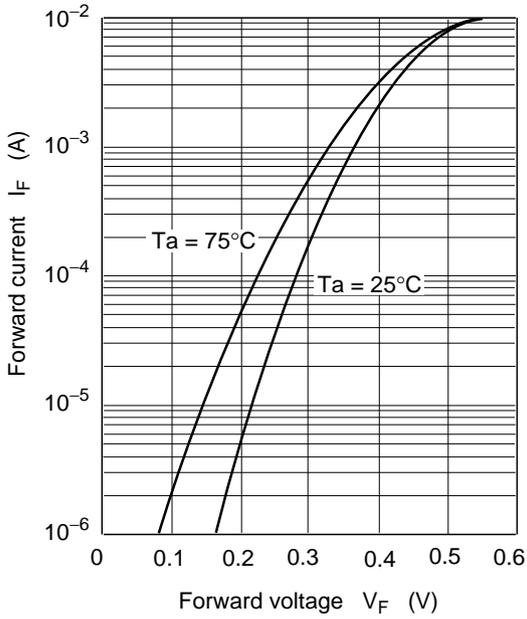


Fig.1 Forward current Vs. Forward voltage

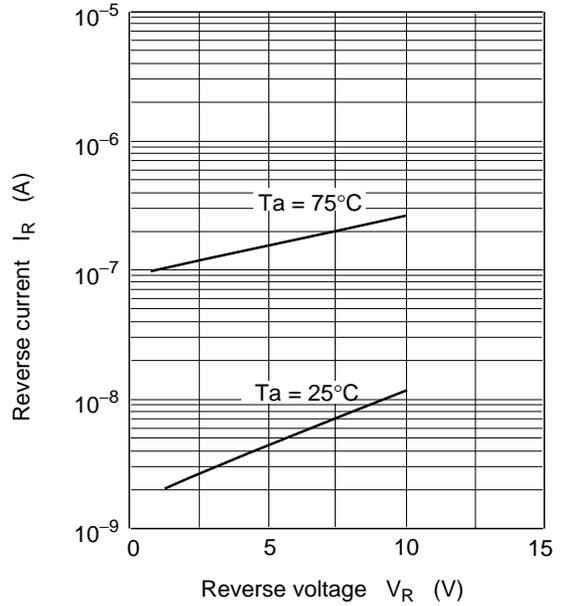


Fig.2 Reverse current Vs. Reverse voltage

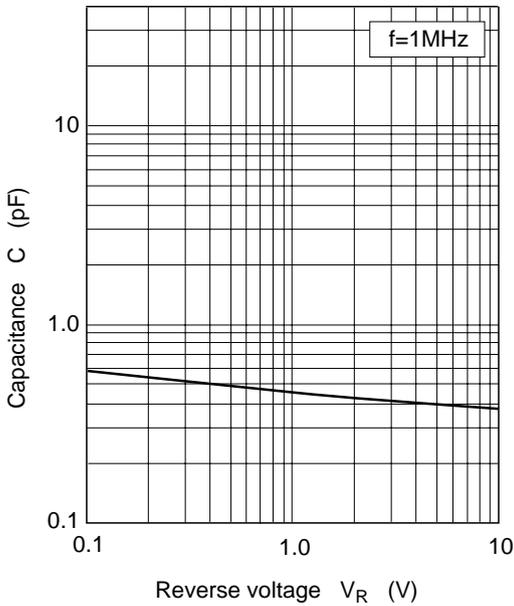
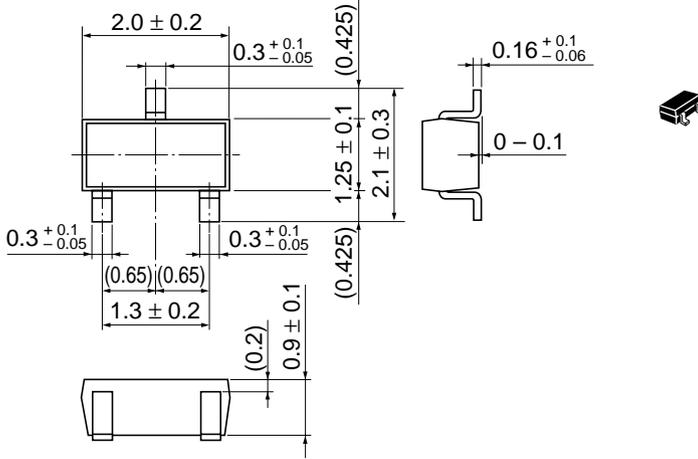


Fig.3 Capacitance Vs. Reverse voltage

## Package Dimensions

Unit: mm



Hitachi Code	CMPAK
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.006 g

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